

Notice of References Cited	Application/Control No. 09/756,971	Applicant(s)/Patent Under Reexamination AKRAM, SALMAN	
	Examiner David A. Zarneke	Art Unit 2827	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
	B	US-			
	C	US-			
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	"Silver", Wikipedia, the Free Encyclopedia from internet site http://www.en.wikipedia.org/wiki/silver
	V	Wagner et al., "Easy Heatsink Mods To Drop CPU Temps", Chron USA, from internet site http://www.overclockers.com/tips188
	W	"Cooling Fundamentals:Thermal Conductivity", from http://www.frostytech.com/articleview.cfm?articleID=233
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.

Notice of References Cited

Application/Control No.

09/756,971

Applicant(s)/Patent Under
Reexamination
AKRAM, SALMAN

Examiner

David A. Zarneke

Art Unit

2827

Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-5,998,860	12-1999	Chan et al.	257/679
*	B	US-6,215,180	04-2001	Chen et al.	257/720
*	C	US-6,255,140	07-2001	Wang, Hsing-Seng	438/122
*	D	US-5,661,086	08-1997	Nakashima et al.	257/668
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
*	U	Tummala et al., Microelectronics Packaging Handbook, Semiconductor Packaging - Part 11, 2nd Edition, 1997, Chapman & Hall, pages 898-901
*	V	Tummala et al., Microelectronics Packaging Handbook, Subsystem Packaging - Part 111, 2nd Edition, 1997, Chapman & Hall, pages 223-234
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.